PERMABOND® ET5364

Two-Part Epoxy

Technical Datasheet

Features & Benefits

- Adhesion to a wide variety of substrates
- Easy to apply
- High shear strength
- Good impact strength
- Good chemical resistance
- Non-drip rheology

Description

PERMABOND® ET5364 is a two-part, 1:1 mixable epoxy adhesive with good adhesion to a variety of substrates such as wood, metal, ceramics and some plastics and composites. Permabond ET5364 forms tough bonds with excellent shear strength.

Physical Properties of Uncured Adhesive

	ET5364A	**ET5364B**
Chemical composition	Epoxy Resin	Polyamine Hardener
Appearance	Cream	Black
Viscosity @ 25°C	20rpm: 90,000-130,000 *(cP)* 2rpm: 400,000-600,000 *(cP)*	20rpm: 60,000-110,000 *(cP)* 2rpm: 200,000-300,000 *(cP)*
Specific gravity	1.35	1.08

Typical Curing Properties

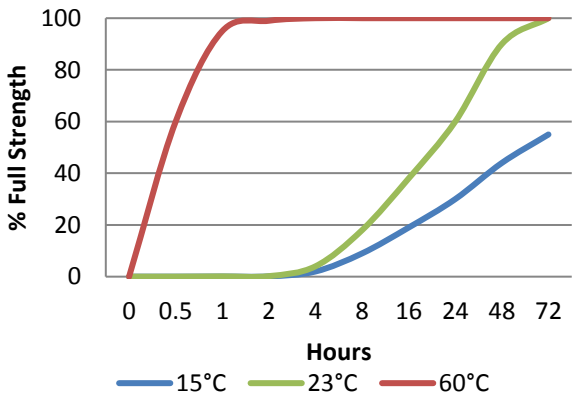
Mix ratio	1:1 by volume 10:8 by weight
Maximum gap fill	2 mm *0.08 in*
Usable / pot life @23°C	2 hours
Handling time @23°C	8 hours
Working strength	@23°C : 24 hours @60°C: 30 mins
Full cure	@23°C: 7 days @60°C: 1 hour

Typical Performance of Cured Adhesive

Shear strength* (ISO4587) cured 72 hrs @ 23°C	Steel: 22-24 N/mm² *(3200-3500 psi)* Aluminium: 24-26 N/mm² *(3500-3800psi)*
Shear strength* (ISO4587)Adhesive cured 1 hour@60°C	Steel: 24-26 N/mm² *(3500-3800 psi)* Aluminium: 28-30 N/mm² *(4100-4350psi)*

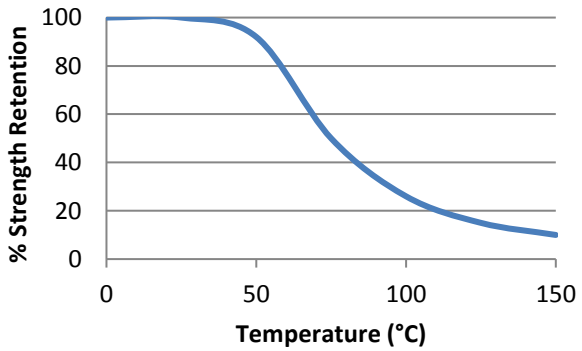
**Strength results will vary depending on the level of surface preparation and gap.*

Strength Development



Graph shows typical strength development of bonded components. An increase of 8°C in temperature will halve the cure time. Lower temperatures will result in a slower cure time.

Hot Strength



"Hot strength" shear strength tests performed on mild steel. Fully cured specimens conditioned to pull temperature for 30 minutes before testing at temperature.

ET5364 can withstand higher temperatures for brief periods (such as for paint baking and wave soldering processes) providing the joint is not unduly stressed. The minimum temperature the cured adhesive can be exposed to is -40°C (-40°F) depending on the materials being bonded.